

DanBond E12

General Purpose Rapid Epoxy Adhesive

DanBond E12 is a rapid curing, multipurpose, two component, room temperature curing, liquid adhesive of high strength and toughness.

It is suited for quick repair and maintenance work and is ideal for industrial series production with short cycle times.

FEATURES:

- Extremely high adhesive force viscous
- Self-levelling
- Very short pot life
- Fast-curing

APPLICATIONS:

- Ideal for bonding all types of Fiberglass, PBT, Epoxy, Wood, RIM, Nylon, FRP, Polyesters, Styrene, Stainless Steel etc.

Technical Data

Composition	Epoxy resin unfilled
Colour	transparent
Mixing ratio by weight (Resin / Hardener)	1:1
Density of the mixture	1,15 g/cm ³
Viscosity of the mixture at 20°C (+68°F)	8.500 mPa·s
Adhesive gap bridging up to max.	2 mm
Processing temperature	+10 to +30 °C
Curing temperature	+6 to +40 °C
Pot-life at 20°C (+68°F) for 10ml material	4 - 5 min.
Handling strength (35% strength) after	30 min.
Capable of bearing mechanical loads (50% strength) after	1 h
Final strength (100%) after	24 h
Medium strength of the pure epoxy resin according to DIN EN 1465	
Pressure	9 Mpa
Pull	40 Mpa
Bending	58 Mpa
Tg after curing at room temperature	44,7 Tg (°C)
Tg after tempering (at 90 °C)	46,1 Tg (°C)
E-Modul	2.000 - 2.500 Mpa
Shore hardness D	65
Medium shear strength according to DIN EN 1465 at	
Steel sand blasted	20 N/mm ²
Alu sandblasted	19 N/mm ²
PVC hard-roughened	13 N/mm ²
Linear shrinkage	2,0 %
Temperature resistance	-50 to +80 °C
Thermal diffusivity (23°C)	0,133 mm ² /s
Thermal conductivity	0,24 W/m·K
Specific heat capacity	1,482 J/(g·K)
Resistivity	1,03 · 10 ¹¹ Ωm

SURFACE PREPERATION

All surfaces must be clean, dry, dust and grease free before application. Use a suitable solvent (acetone or isopropanol) for the degreasing of most surfaces.

Best result will be achieved with surfaces that have been lightly abraded immediately prior to bonding.

Directions for Use

Cartridges:

- 1) Insert the cartridge into the application gun
- 2) Remove the cartridge end cap and dispense a small amount of material to balance the cartridge.
- 3) Attach the correct static mixer to the end of the cartridge and begin dispensing the material.
- 4) Apply material to one of the substrates and then join the parts. Parts must be joined within the working time of the adhesive
- 5) Excess adhesive can be wiped away with organic solvent.

Adhesive bond should be allowed to develop full strength before subjecting to any service loads.

PACKAGING

DanBond E12 is available in 50 ml and 200 ml Cartridges.

HANDLING PRECAUTIONS

Please refer to the relevant SDS (Safety Data Sheet) regarding the safe handling of this material.

Note: *All materials, whether innocuous or not, should be handled in accordance with the principles of good industrial hygiene.*

Further technical support or information may be obtained from

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